# **12-Stage Binary Ripple** Counter

The MC74AC4040 consists of 12 master-slave flip-flops. The output of each flip-flop feeds the next and the frequency at each output is half that of the preceding one. The state of the counter advances on the negative-going edge of the Clock input. Reset is asynchronous and active-high.

State changes of the Q outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and may have to be gated with the Clock of the MC74AC4040 for some designs.

## Features

- 140 MHz Typ. Clock
- Outputs Source/Sink 24 mA
- Operating Voltage Range: 2.0 to 6.0 V
- High Noise Immunity
- Pb–Free Packages are Available

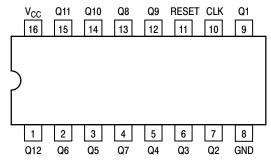


Figure 1. Pinout: 16–Lead Packages Conductors (Top View)

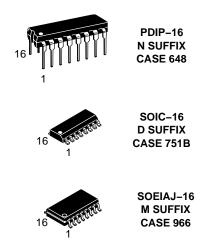
## **FUNCTION TABLE**

Clock	Reset	Output State
	L	No Change
	L	Advance to next state
Х	Н	All Outputs are low



## **ON Semiconductor®**

http://onsemi.com



## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74AC4040N	PDIP-16	25 Units/Rail
MC74AC4040NG	PDIP-16 (Pb-Free)	25 Units/Rail
MC74AC4040D	SOIC-16	48 Units/Rail
MC74AC4040DG	SOIC-16 (Pb-Free)	48 Units/Rail
MC74AC4040DR2	SOIC-16	2500 Tape & Reel
MC74AC4040DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74AC4040M	SOEIAJ-16	50 Units/Rail

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 4 of this data sheet.

## MC74AC4040

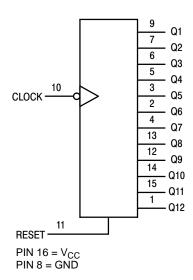


Figure 2. Logic Diagram

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage (Referenced to GND)	–0.5 to V <sub>CC</sub> +0.5	V
V <sub>OUT</sub>	DC Output Voltage (Referenced to GND)	–0.5 to V <sub>CC</sub> +0.5	V
I <sub>IN</sub>	DC Input Current, per Pin	±20	mA
I <sub>OUT</sub>	DC Output Current, per Pin	±50	mA
I <sub>CC</sub>	DC V <sub>CC</sub> or GND Current per Output Pin	±50	mA
P <sub>D</sub>	Power Dissipation in Still Air Plastic† SOIC Package†	750 500	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 seconds (Plastic DIP or SOIC Package)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating: Plastic DIP: - 10mW/°C from 65°C to 125°C SOIC Package: -7.0 mW/°C from 65°C to 125°C

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>IN</sub> /V <sub>OUT</sub>	Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	-
T <sub>A</sub>	Operating Temperature, All Package Types	-40	+85	°C
t <sub>r</sub> /t <sub>f</sub>	Input Rise/Fall Time $V_{CC} = 3.0 \text{ V}$ (Figure 1) $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 5.5 \text{ V}$	0 0 0	150 40 25	ns/V

## MC74AC4040

## DC CHARACTERISTICS (unless otherwise specified)

Symbol	Parameter	Value	Unit	
ICC	Maximum Quiescent Supply Voltage	80	μΑ	$V_{in} = V_{CC}$ or GND $V_{CC} = 5.5$ V, $T_A =$ Worst Case
I <sub>CC</sub>	Maximum Quiescent Supply Current	8.0	μΑ	$V_{in} = V_{CC}$ or GND $V_{CC} = 5.5$ V, $T_A = 25^{\circ}C$

## **DC CHARACTERISTICS**

			74	AC	74AC						
		V <sub>CC</sub>	T <sub>A</sub> = +25°C		T <sub>A</sub> = +25°C		$T_{A} = +25^{\circ}C$		T <sub>A</sub> = −40°C to +85°C		
Symbol	Parameter	(V)	Тур	G	uaranteed Limits	Unit	Conditions				
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0 4.5 5.5		2.1 3.15 3.85	2.1 3.15 3.85	V	$V_{OUT} = 0.1 V$ or $V_{CC} - 0.1 V$				
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0 4.5 5.5	- - -	0.9 1.35 1.65	0.9 1.35 1.65	V	$V_{OUT} = 0.1 V$ or $V_{CC} - 0.1 V$				
V <sub>OH</sub>	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I <sub>OUT</sub> = –50 μA				
		3.0 4.5 5.5	- -	2.56 3.86 4.86	2.46 3.76 4.76	V	$V_{IN} = V_{IL} \text{ or } V_{IH}$ -12 mA $I_{OH}$ -24 mA -24 mA				
V <sub>OL</sub>	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	Ι <sub>ΟUT</sub> = 50 μΑ				
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	$\label{eq:VIN} \begin{array}{c} {}^{*}V_{IN} = V_{IL} \text{ or } V_{IH} \\ 12 \text{ mA} \\ I_{OL} \qquad 24 \text{ mA} \\ 24 \text{ mA} \end{array}$				
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	$V_{I} = V_{CC}, GND$				
I <sub>OLD</sub>	Minimum Dynamic Output Current†	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max				
I <sub>OHD</sub>		5.5	-	-	-75	mA	V <sub>OHD</sub> = 3.85 V Min				

\*All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

## MC74AC4040

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D
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				74AC		74/	AC		
		V <sub>CC</sub> *		<sub>A</sub> = +25° <sub>L</sub> = 50 p		$T_A = -40^\circ C$ $C_L = 5$			
Symbol	Parameter	(V)	Min	Тур	Max	Min	Max	Unit	Fig. No.
f <sub>max</sub>	Maximum Clock Frequency	3.3 5.0	110 130	120 140		100 120	-	MHz	-
n <sub>CP</sub> to Q1	Propagation Delay n <sub>CP</sub> to Q1	3.3 5.0	2.0 2.0		11 8.0	2.0 2.0	14 10	ns	-
Q <sub>n</sub> to Q <sub>n</sub> +1	Propagation Delay $Q_n$ to $Q_n +1$	3.3 5.0	0 0	-	5.5 3.5	0 0	6.5 4.5	ns	-
MR to Q t <sub>HL</sub>	Propagation Delay MR to Q	3.3 5.0	3.0 3.0	-	12 10	3.0 3.0	15 12	ns	-
t <sub>rec</sub> n <sub>CP</sub> to MR	Recovery Time	3.3 5.0	0 0	-2.5 -1.5	-	0 0		ns	_
t <sub>w</sub> n <sub>CP</sub>	Minimum Pulse Width Clock Pin	3.3 5.0	4.0 3.0	3.5 2.5	-	4.5 3.5		ns	-
t <sub>w</sub> MR	Minimum Pulse Width Master Reset	3.3 3.0	4.0 3.0	3.5 2.5	-	4.5 3.5	-	ns	_

\*Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. \*Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

## CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	50	pF	V <sub>CC</sub> = 5.0 V

## MARKING DIAGRAMS

#### PDIP-16

PDIP-16	SOIC-16
ഫറവവവ	<u>_                                    </u>
MC74AC4040N	AC4040G o AWLYWW

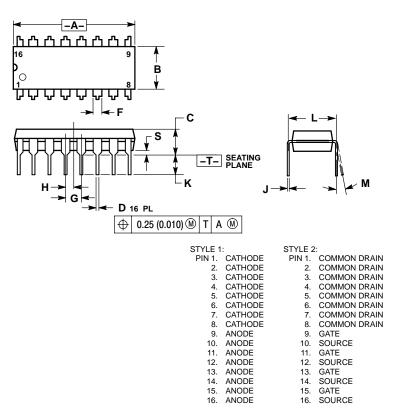
А	= Assembly Location
WL, L	= Wafer Lot
YY, Y	= Year
WW, W	= Work Week
G	= Pb-Free Package

### SOEIAJ-16

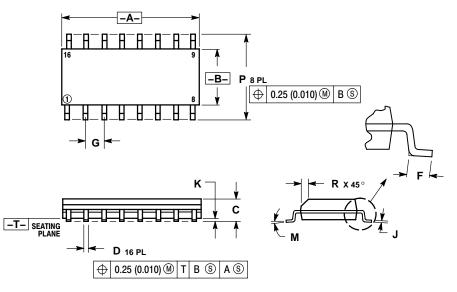


## PACKAGE DIMENSIONS

PDIP-16 CASE 648-08 ISSUE T



SOIC CASE 751B-05 ISSUE J



NOTES:

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

- DIMENSION B DOES NOT INCLUDE 4.
- MOLD FLASH. 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
κ	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- 3.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) 4.

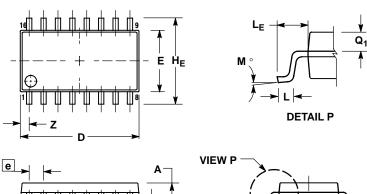
PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR 5.

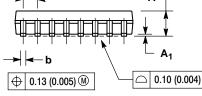
PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

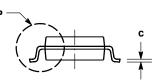
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
ſ	0.19	0.25	0.008	0.009
Κ	0.10	0.25	0.004	0.009
Μ	0 °	7°	0 °	7°
Ρ	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

## PACKAGE DIMENSIONS

SOEIAJ-16 CASE 966-01 **ISSUE A** 







NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI 1. Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED 3 AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR 4
- REFERENCE ONLY. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE 5 DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018)

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
М	0 °	10 °	0 °	10 °
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Ζ		0.78		0.031

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